

HSL276A

Silicon Schottky Barrier Diode for Detector

REJ03G0528-0100 Rev.1.00 Feb 09, 2005

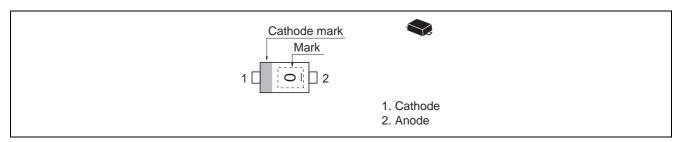
Features

- High forward current, Low capacitance.
- Extremely small Flat Lead Package (EFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Renesas Code	Previous Code	
HSL276A	0	PXSF0002ZA-A	EFP	

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit	
Repetitive peak reverse voltage	V _{RRM}	5	V	
Reverse voltage	V _R	3	V	
Average rectified current	I ₀	30	mA	
Junction temperature	Tj	125	°C	
Storage temperature	Tstg	−55 to +125	°C	

Electrical Characteristics

 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse voltage	V _R	3.0	_	_	V	I _R = 1 mA
Reverse current	I _R	_	_	50	μΑ	V _R = 0.5 V
Forward current	I _F	35	_	_	mA	V _F = 0.5 V
Capacitance	С	_	_	0.85	pF	V _R = 0.5 V, f = 1 MHz
ESD-Capability *1	_	30	_	_	V	C = 200 pF, R_L = 0 Ω , Both forward and reverse direction 1 pulse.

Notes: 1. Failure criterion ; $I_R > 100 \ \mu A$ at V_R =0.5 V

- 2. Please do not use the soldering iron due to avoid high stress to the EFP package.
- 3. The material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

Main Characteristic

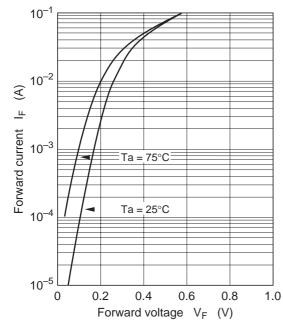


Fig.1 Forward current vs. Forward voltage

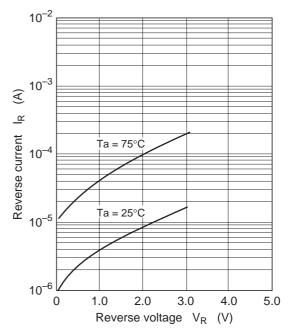
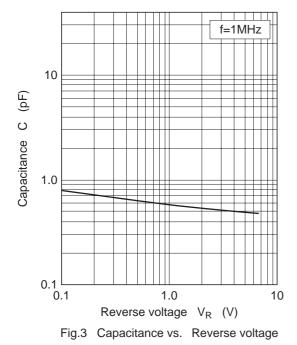
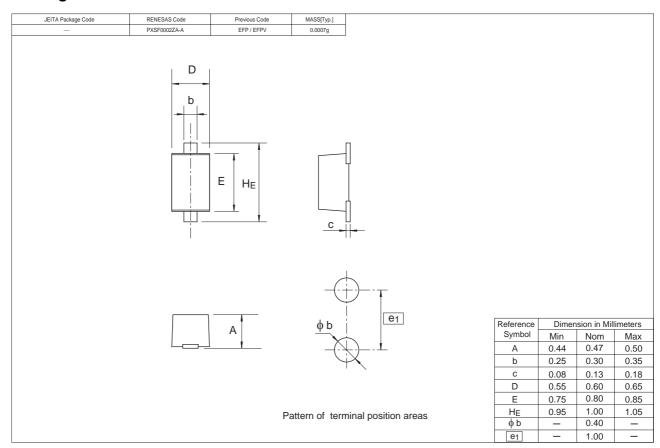


Fig.2 Reverse current vs. Reverse voltage



Package Dimensions



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